

Wafer Product Datasheet (Addendum)

Product / ID	AT25SL128A-DWF / 25M4AA																																																																																										
Description	128 Mbit, 1.7V Minimum SPI Serial Flash Dual IO, Quad IO. QPI Support																																																																																										
Die Image	<p style="text-align: center;">die orientation to wafer notch</p>																																																																																										
Dimensions & Coordinates	<table border="1" style="width: 100%; border-collapse: collapse; text-align: center;"> <thead> <tr> <th rowspan="2"></th> <th colspan="2">Dimensions & Pad Coordinates</th> <th rowspan="2">DataSheet Pin Assignment</th> <th rowspan="2">Pad No. () on die diagram</th> </tr> <tr> <th>X (um)</th> <th>Y (um)</th> </tr> </thead> <tbody> <tr> <td>Die Size</td> <td>2992</td> <td>3160</td> <td>N/A</td> <td>N/A</td> </tr> <tr> <td>Scribe Line Width</td> <td>60</td> <td>60</td> <td>N/A</td> <td>N/A</td> </tr> <tr> <td>Die Step</td> <td>3052</td> <td>3220</td> <td>N/A</td> <td>N/A</td> </tr> <tr> <td>Pad Opening</td> <td>65</td> <td>65</td> <td>N/A</td> <td>N/A</td> </tr> <tr> <td>/CS</td> <td>-1232</td> <td>-1234</td> <td>1</td> <td>1</td> </tr> <tr> <td>SO (IO₁)</td> <td>-1418</td> <td>-1234</td> <td>2</td> <td>2</td> </tr> <tr> <td>/WP (IO₂)</td> <td>-1418</td> <td>-1364</td> <td>3</td> <td>3</td> </tr> <tr> <td>/CS2</td> <td>-1418</td> <td>-1446</td> <td>NC</td> <td>4</td> </tr> <tr> <td>GND</td> <td>-1390</td> <td>-1576</td> <td>4</td> <td>5</td> </tr> <tr> <td>GND</td> <td>-1304</td> <td>-1576</td> <td>4</td> <td>6</td> </tr> <tr> <td>SI (IO₀)</td> <td>1406</td> <td>-1576</td> <td>5</td> <td>7</td> </tr> <tr> <td>CLK</td> <td>1406</td> <td>-1494</td> <td>6</td> <td>8</td> </tr> <tr> <td>/HOLD (IO₃)</td> <td>1418</td> <td>-1300</td> <td>7</td> <td>9</td> </tr> <tr> <td>RSTb</td> <td>1336</td> <td>-1300</td> <td>8</td> <td>10</td> </tr> <tr> <td>VCC</td> <td>1254</td> <td>-1300</td> <td>8</td> <td>11</td> </tr> <tr> <td>VCC</td> <td>1174</td> <td>-1300</td> <td>8</td> <td>12</td> </tr> </tbody> </table>					Dimensions & Pad Coordinates		DataSheet Pin Assignment	Pad No. () on die diagram	X (um)	Y (um)	Die Size	2992	3160	N/A	N/A	Scribe Line Width	60	60	N/A	N/A	Die Step	3052	3220	N/A	N/A	Pad Opening	65	65	N/A	N/A	/CS	-1232	-1234	1	1	SO (IO ₁)	-1418	-1234	2	2	/WP (IO ₂)	-1418	-1364	3	3	/CS2	-1418	-1446	NC	4	GND	-1390	-1576	4	5	GND	-1304	-1576	4	6	SI (IO ₀)	1406	-1576	5	7	CLK	1406	-1494	6	8	/HOLD (IO ₃)	1418	-1300	7	9	RSTb	1336	-1300	8	10	VCC	1254	-1300	8	11	VCC	1174	-1300	8	12
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Part Number Ordering Code	Operating Temperature Range	Functional Specification
AT25SL128A-DWF	-40°C to 85°C	https://www.adestotech.com/wp-content/uploads/AT25SL128A_109.pdf

Revision Level - Release Date	History
A - September 2018	Initial Release

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